## **MA2C029**

## Silicon epitaxial planar type

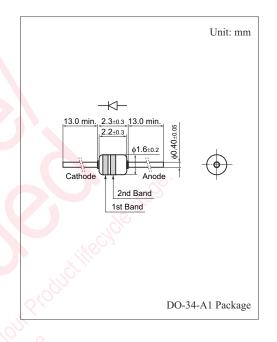
For reduced voltage and temperature compensation

#### ■ Features

- High reliability achieved through combination of a planar type chip and glass sealing structure
- Easy mounting because of employing DO-35 (DHD) envelope
- Extremely small reverse current I<sub>R</sub>
- $\bullet$  Large power dissipation  $P_{\rm D}$
- Wide forward voltage V<sub>F</sub> range

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	6	V
Forward current (Average)	I <sub>F(AV)</sub>	50	mA
Power dissipation	P <sub>D</sub>	150	mW
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C



### ■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C^{*1}$

Parameter	Symbol	Conditions Min Typ	Max	Unit
Forward current	$V_{F1}$	$I_F = 1.5 \text{ mA}$ 2 *2	1161	V
	$V_{F2}$	$I_F = 50 \text{ mA}$	1.1	v
Reverse current	$I_R$	$V_R = 6 V$	10	μΑ
Temperature coefficient of forward voltage *3	$-\Delta V_F/V_T$	$I_F = 1.5 \text{ mA}$ 2.0		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. \*1: The temperature must be controlled 25°C for  $V_F$  mesurement.  $V_F$  value measured at other temperature must be adjusted to  $V_F$  (25°C)

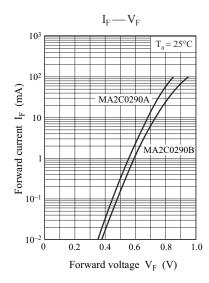
1.	The temperature in	last be controlled	
*2:	Туре	V <sub>F</sub> (V)	
	MA2C0290A	0.56 to 0.61	
	MA2C0290A1	0.56 to 0.59	
	MA2C0290A2	0.58 to 0.61	
	MA2C0290B	0.59 to 0.64	
	MA2C0290B1	0.59 to 0.62	
	MA2C0290B2	0.61 to 0.64	

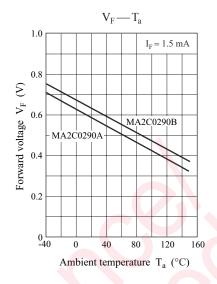
<sup>\*3:</sup>  $T_i = 25^{\circ}C$  to  $150^{\circ}C$ 

#### ■ Cathode Indication

Type No.	MA2C0290A	MA2C0290A1	MA2C0290A2	MA2C0290B	MA2C0290B1	MA2C0290B2
1st band color	Red	Red	Red	Blue	Blue	Blue
2nd band color	_	Blue	Yellow	_	Blue	Yellow

MA2C029 Panasonic





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